

ABSTRACT

A print mask is used to form bumps on barrier metal layers of a wafer. The mask comprises a plurality of elongated perforations disposed in a linear arrangement such that paste 5 can be applied to an object to be printed on via the perforations. Each of the perforations includes an edge disposed along the longitudinal direction, and the edge is inclined with respect to the direction perpendicular to the direction of arranging the perforations.